



Product Change Notification

112974 - 01

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Should you have any issues with the timeline or content of this change, please contact the Intel Representative(s) for your geographic location listed below. No response from customers will be deemed as acceptance of the change and the change will be implemented pursuant to the key milestones set forth in this attached PCN.

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Product Change Notification

Change Notification #:	112974 - 01
Change Title:	Intel® 82599EB 10 Gigabit Ethernet Controller, Tape JL82599EB MM#903142, Intel® 82599EB 10 Gigabit Ethernet Controller, Tray JL82599EB MM#903143, Intel® 82599EN 10 Gigabit Ethernet Controller, Tape JL82599EN MM#917841, Intel® 82599EN 10 Gigabit Ethernet Controller, Tray JL82599EN MM#917842, Intel® 82599ES 10 Gigabit Ethernet Controller, Tray JL82599ES MM#903140, Intel® 82599ES 10 Gigabit Ethernet Controller, Tape JL82599ES MM#903139 PCN 112974-01, Product Discontinuance Change to PB Free, End of Life for existing SKUs Reason for Revision: Add S-Codes for Post conversion products
Date of Publication:	June 17, 2014

Key Characteristics of the Change:
Product Discontinuance

Forecasted Key Milestones:

Last Product Discontinuance Order Date:	Dec 26, 2014
Last Product Discontinuance Shipment Date:	Jun 26, 2015

Description of Change to the Customer:

Reason for Revision: Add S-Codes for Post conversion products

The order codes listed in affected products table below are being EOL'd and customers will need to place orders under the new codes. Also, as part of this transition from eutectic to lead free at the FLI style of the product marking will change. The mark will go to a laser mark on swatch versus an ink stamp on substrate as illustrated below.



Niantic Eutectic (Pb-bumps)



Niantic Lead-free

In order to be compliant with Intel's corporate Green initiative, Intel is moving these products from RoHS Compliant Leaded FLI (First Level Interconnect) products to RoHS Compliant 100% Lead Free (LF) FLI products. There is no Form, Fit, or Function or die changes on any of the impacted silicon. Intel anticipates no impact to the customer. Since this is an internal package change to provide a material solution that is RoHS compliant, Intel has qualified and certified this change in the same way as all products supplied to our customers. The customer could use either pre-PCN or Post-PCN material in the same way with no change to electrical performance, mechanical use, or stated reliability.

Customer Impact of Change and Recommended Action:

These new MM#s do not reflect a change to the silicon die for the impacted controllers and was used for factory identification and tracking for the new components. There is no form-fit-function change for any of the impacted silicon.

FLI (First Level Interconnect) material will change from Lead (Pb) based solder bump technology to Pb-Free (Sn/Ag) technology.

There is no change to the second level interconnects for these products. This change affects First Level Interconnects only.

Material Master numbers (MM#'s) will change to the new LF MM#'s, as shown in the products affected table within this PCN notice.

Customers should review their demand forecasts and plan accordingly to place all orders by the Last Order Date of December 26, 2014, and plan for receipt of all shipments no later than June 26, 2015. Supply may be limited based on business conditions that may require either pull in or extension of the LOD/LSD at Intel's sole discretion. All orders booked after this announcement, are considered non-cancelable. There are replacement SKUs that are available, but may require customer requalification, so customers are encouraged to work closely with their local Intel Sales representatives to plan for a smooth transition including any final purchases to support customer-sponsored repair or warranty beyond the terms of this PDN. Intel recommends customers migrate new designs to the Intel® 82599 10 Gigabit Ethernet Controller Family.

Products Affected / Intel Ordering Codes:

Marketing Name	Product Code	S-Spec	MM#	Stepping	Recommended Replacement Product Code	S-Spec	Recommended Replacement MM#
Intel® 82599ES 10 Gigabit Ethernet Controller Tape	JL82599ES	S LGWE	903139	B0	JL82599ES	S R1VM	934599
Intel® 82599ES 10 Gigabit Ethernet Controller Tray	JL82599ES	S LGWF	903140	B0	JL82599ES	S R1VN	934600
Intel® 82599EB 10 Gigabit Ethernet Controller Tape	JL82599EB	S LGWG	903142	B0	JL82599EB	S R1W6	934908
Intel® 82599EB 10 Gigabit Ethernet Controller Tray	JL82599EB	S LGWH	903143	B0	JL82599EB	S R1W7	934915
Intel® 82599EN 10 Gigabit Ethernet Controller Tape	JL82599EN	S LJFT	917841	B0	JL82599EN	S R1ZR	936722
Intel® 82599EN 10 Gigabit Ethernet Controller Tray	JL82599EN	S LJFU	917842	B0	JL82599EN	S R1ZS	936723

PCN Revision History:

Date of Revision:	Revision Number:	Reason:
May 20, 2014	00	Originally Published PCN
June 17, 2014	01	Add S-Codes for Post conversion products